

Title (en)

COOLING DEVICE FOR COOLING A PLURALITY OF HEAT-EMITTING ELECTRONIC COMPONENTS ARRANGED ON A CIRCUIT BOARD, AND SYSTEM COMPRISING THE COOLING DEVICE

Title (de)

KÜHLVORRICHTUNG ZUR KÜHLUNG EINER VIELZAHL VON AUF EINER PLATINE ANGEORDNETEN UND WÄRME ABGEBENDEN ELEKTRONIKKOMPONENTEN SOWIE SYSTEM UMFASSEND DIE KÜHLVORRICHTUNG

Title (fr)

DISPOSITIF DE REFROIDISSEMENT POUR REFROIDIR UNE PLURALITÉ DE COMPOSANTS ÉLECTRONIQUES ÉMETTEURS DE CHALEUR DISPOSÉS SUR UN CIRCUIT IMPRIMÉ, ET SYSTÈME COMPRENANT LE DISPOSITIF DE REFROIDISSEMENT

Publication

**EP 4052549 A1 20220907 (DE)**

Application

**EP 20771243 A 20200907**

Priority

- DE 102019135101 A 20191219
- EP 2020074952 W 20200907

Abstract (en)

[origin: WO2021121688A1] The invention relates to a cooling device (1) for cooling a plurality of heat-emitting electronic components (3) arranged on a circuit board (2). The cooling device (1) comprises a distributing unit (10) and at least one cooling satellite (20). The distributing unit has a coolant inlet (11) and a coolant outlet (12), and a coolant can flow through the distributing unit from its coolant inlet (11) to its coolant outlet (12) along a predefined and fixed coolant path (P). The at least one cooling satellite (20) is fixed on the distributing unit (10) in a spatial position that is predefined with respect to the distributing unit (10), and the at least one cooling satellite has a heat sink (23), a coolant inlet (21) and a coolant outlet (22). The heat sink (23) can be brought into face-to-face contact with at least one electronic component (3) of the plurality of electronic components (3). The coolant can flow through the cooling satellite (20) from its coolant inlet (21) to its coolant outlet (22) along the coolant path (P). The coolant path (P) runs through the distributing unit (10) and the at least one cooling satellite (20) and at least partly along the heat sink (23) of the cooling satellite (20).

IPC 8 full level

**H05K 7/20** (2006.01)

CPC (source: EP KR)

**H05K 7/20254** (2013.01 - EP KR); **H05K 7/20272** (2013.01 - KR)

Citation (search report)

See references of WO 2021121688A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**DE 102019135101 A1 20210624**; CN 114902822 A 20220812; EP 4052549 A1 20220907; JP 2023507205 A 20230221; KR 20220118474 A 20220825; WO 2021121688 A1 20210624

DOCDB simple family (application)

**DE 102019135101 A 20191219**; CN 202080087578 A 20200907; EP 2020074952 W 20200907; EP 20771243 A 20200907; JP 2022538210 A 20200907; KR 20227024111 A 20200907